

# EUROPEAN PATENT OFFICE

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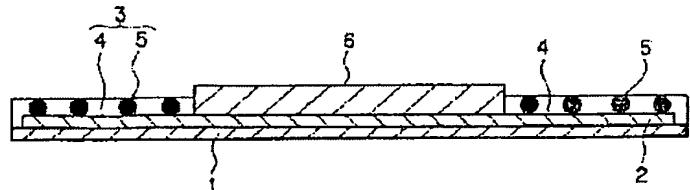
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TITLE : INSULATING ADHESIVE,  
ANISOTROPICALLY  
ELECTROCONDUCTIVE ADHESIVE,  
HEAT SEALING CONNECTOR, AND  
MANUFACTURING METHOD FOR  
HEAT SEALING CONNECTOR

ABSTRACT : PROBLEM TO BE SOLVED: To provide an insulating adhesive, an anisotropically electroconductive adhesive and a heat sealing connector which are capable of ensuring an electrical connection while maintaining a high reliability even when acted by a high temperature or a thermal shock and capable of keeping well the initial adhesive strength and the adhesion holding power and also have a long pot life, and to provide a manufacturing method for the heat sealing connector.

SOLUTION: The insulating adhesive 4 is produced from a solid bisphenol-type epoxy resin having an epoxy equivalent of 1,000-9,000, a liquid bisphenol-type epoxy resin having an epoxy equivalent of 160-300, a hardener for the epoxy resins and an ultraviolet ray curable-type resin. The anisotropically electroconductive adhesive 3 is produced by blending 100 pts. by volume of the insulating adhesive 4 and 0.1-50 pts. by volume of electroconductive particles 5. A flexible substrate 1 is provided on at least one side surface with an electroconductive line 2, and at least the connection part of which electroconductive line 2 is provided with the anisotropically electroconductive adhesive 3.

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